


**Property Table (Flame retardant PC alloy grade)**


Features				High flow Standard	High flow High impact	Filler reinforced High Stiffness Dimensional Precision				
Grades				SK2706	SK2708	SK3730				
Properties	Units	Test Method	condition	>PC+ABS-FR(40)<	>PC+ABS-FR(40)<	>PC+AS-(TD+PD)30-FR(40)<				
Density	g/cm <sup>3</sup>	ISO 1183 (JIS K7112)		1.21	1.19	1.43				
Water Absorption	%	ISO 62 (JIS K7209)	24h 50%RH	0.1	0.1	—				
<b>Fluidity</b>										
Melt Volume-Flow Rate (MVR)	cm <sup>3</sup> /10min	ISO 1133 (JIS K7210)		260℃ 2.16kg 20	260℃ 2.16kg 23	260℃ 2.16kg 8				
Spiral Flow Length	cm	Idemitsu Method		Thickness:2mm/Width:10mm Cylinder:240℃/Mold:40℃ Inj.Pressure:125MPa 40	Thickness:2mm/Width:10mm Cylinder:240℃/Mold:40℃ Inj.Pressure:125MPa 45	Thickness:2mm/Width:10mm Cylinder:240℃/Mold:40℃ Inj.Pressure:125MPa 22				
<b>Mechanical properties</b>										
Tensile Stress at Yield*1	MPa	ISO 527-1,2 (JIS K7161, 7162)		Y64	Y64	74				
Nominal tensile strain at break*2	%			tB50	tB60	1.5				
Flexural Strength	MPa	ISO 178 (JIS K7171)		90	96	113				
Flexural Modulus	GPa			3	2.9	9				
Charpy Impact Strength	kJ/m <sup>2</sup>	ISO 179-1 (JIS K7111)	notched at 23℃	10	10	3				
Rockwell Hardness	—	ISO 2039-2 (JIS K7202-2)	R scale/ M scale	—	—	—				
<b>Thermal properties</b>										
Temperature of deflection under load	℃	ISO 75-1,2 (JIS K7191-1,2)	0.45MPa 1.8MPa	88 78	88 78	— 100				
Linear Thermal Expansion coefficient	×10 <sup>-5</sup> /℃	ISO 11359-2		5.8	6.5	(MD/TD)2.3/4.5				
Mould Shrinkage	%	Idemitsu Method	2mm MD	0.4	0.3~0.4	0.17				
	%		2mm TD	0.4	0.3~0.4	0.19				
<b>Flammability</b>										
Flammability Rating	mm thickness	UL94	class/mini-thickness	V-1/0.58 V-0/1.0 5VB/0.8	V-1/0.9 V-0/1.5 5VB/1.2	V-1/1.5(BK, NC) 5VB /2.0(BK, NC)				
Thermal Index RTI Elec	℃	UL746B		60	85	50				
RTI Imp				60	85	50				
RTI Str				60	85	50				
<b>Electrical properties</b>										
Dielectric Strength	kV/mm	IEC 60243-1 (JIS C2110)		36.3	—	—				
Arc Resistance	PLC level	ASTM D495		—	—	—				
Volume Resistivity	Ω·cm	ASTM D257		—	—	—				
Dielectric Constant	—	IEC 60250	1MHz	—	—	—				
Dielectric dissipation Factor	—		1MHz	—	—	—				
<b>Standard Molding Parameters</b>										
Cylinder Temperature				240~270℃ (Maximum280℃)	240~270℃ (Maximum280℃)	270~280℃ (Maximum290℃)				
Mold Temperature				40~70℃	40~70℃	40~70℃				
Pre-drying condition				80℃, 5~8hours	80℃, 5~8hours	80~100℃, 5~8hours				

\*1 Y:Yield strength

\*2 tB : Nominal tensile strain at break

◇Data in this Catalogue shows sample figures measured under certain specific conditions.

◇Usage of the products in this catalogue does not warrant any successful results of applications of the products for specific usage.

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◇You should not use the products in medical equipment and medical product applications.

◇Flammability rating in this Catalogue was evaluated with small-scale test method and it is not intended to reflect fire proof performance in case of actual fire.

◇Please verify whether the grade of products to be used for food utensils, cookware or packaging applications supplied by idemitsu will meet the requirement of applicable laws (ex. food sanitation law in japan, etc.) and ordinances in advance.

◇Please verify whether products using raw materials supplied by Idemitsu with applicable laws and ordinances.

◇Please agree to the quality specification in advance if you purchase our products.

◇Figures of physical characteristics of other producer's resins have been referred from their catalogues and information source thereof.

◇Please note that the content of this Catalogue may be altered from time of time according to the improvement of the products without prior notice.

◇In case of exporting the product, please pay attention to the laws and regulations of chemical substances and other substances in the exporting country. For inquiries regarding the applicability of our products to individual laws and regulations, please consult our HP contact or sales staff.